

### Features

- $I_o$  0.8A
- $V_{RRM}$  200V~800V
- Glass passivated chip
- High surge forward current capability
- Supersmall size
- Component in accordance to ROHS 2002/95/EC and WEEE2002/96/WC
- Halogen Free product

### Mechanical data

**Case:** ZB(SMD)

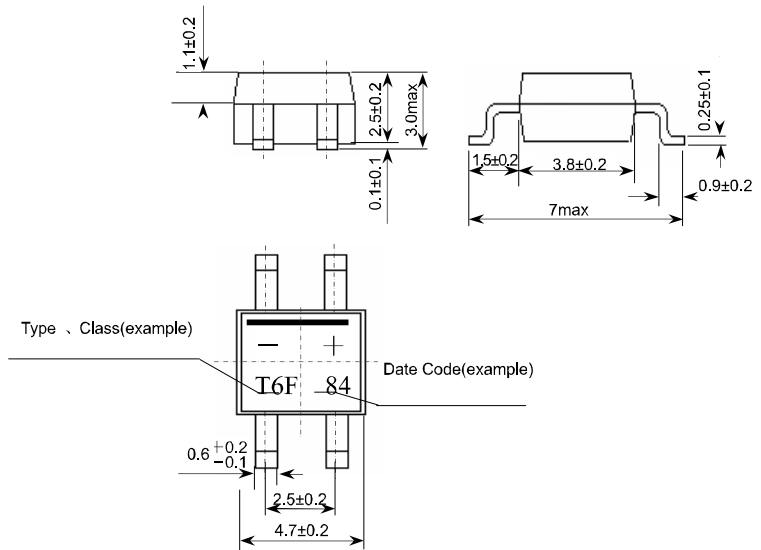
Epoxy meets UL 94V-0 flammability rating

**Terminals:** Pure tin plated leads, solderable per J-STD-002 and JESD22-B102, E3

suffix for consumer grade, meet JESD201 class 1A whisker test.

**Polarity:** As marked on body

### Outline Dimensions and Mark (Unit: mm)



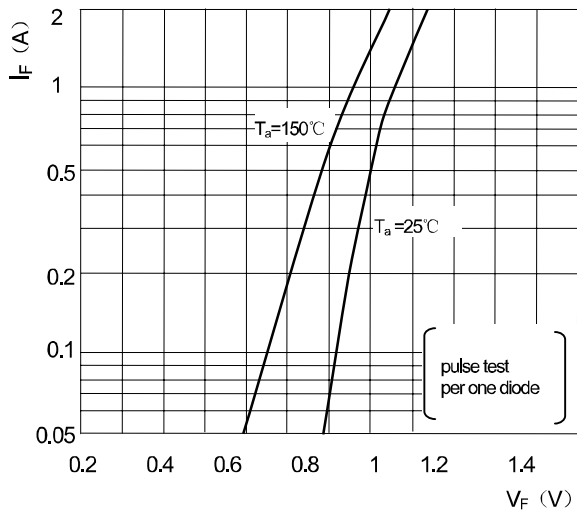
### Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	T1ZB			
				20F	40F	60F	80F
Storage Temperature	$T_{stg}$	°C		-40 ~ +150			
Junction Temperature	$T_j$	°C		+150			
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		200	400	600	800
Average Rectified Output Current	$I_o$	A	50Hz sine wave, R-load, $T_a=25^\circ\text{C}$	On alumina substrate			
				On glass-epoxi substrate			
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	50Hz sine wave, 1 cycle, $T_a=25^\circ\text{C}$	30			

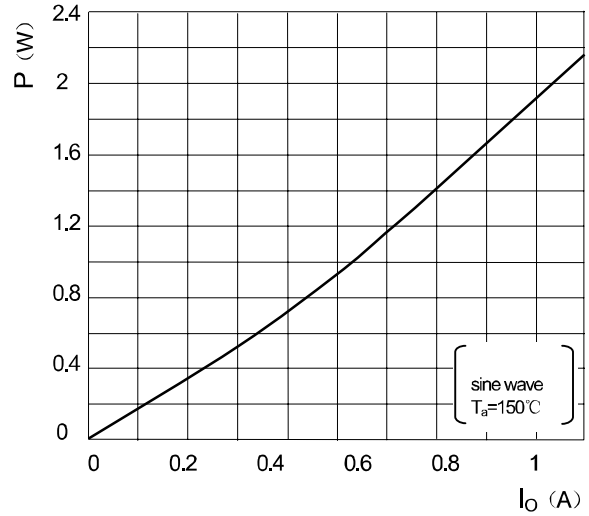
### Electrical Characteristics ( $T_a=25^\circ\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	Max
Peak Forward Voltage	$V_{FM}$	V	$I_{FM}=0.4\text{A}$ , Pulse measurement, Rating of per diode	1.05
Peak Reverse Current	$I_{RRM1}$	$\mu\text{A}$	$V_{RM}=V_{RRM}$ , Pulse measurement, Rating of per diode	10
Thermal Resistance	$R_{\theta J-A}$	°C/W	Between junction and ambient, On alumina substrate	76
			Between junction and ambient, On glass-epoxi substrate	134
	$R_{\theta J-L}$		Between junction and lead	20

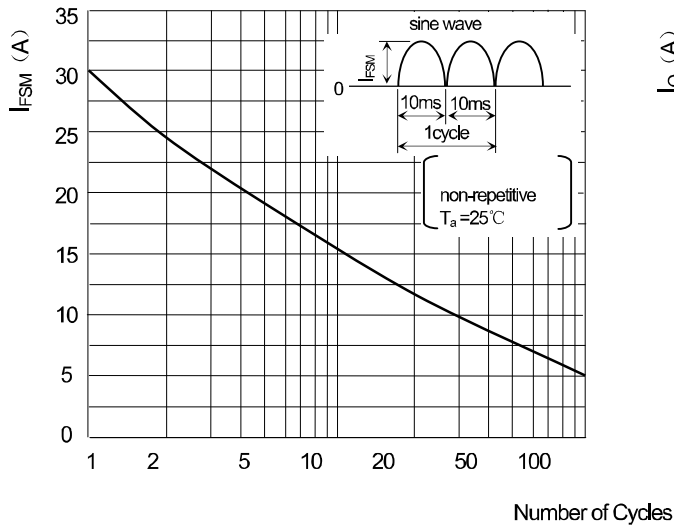
RATINGS AND CHARACTERISTICS CURVES ( $T_A = 25^\circ\text{C}$  unless otherwise noted)



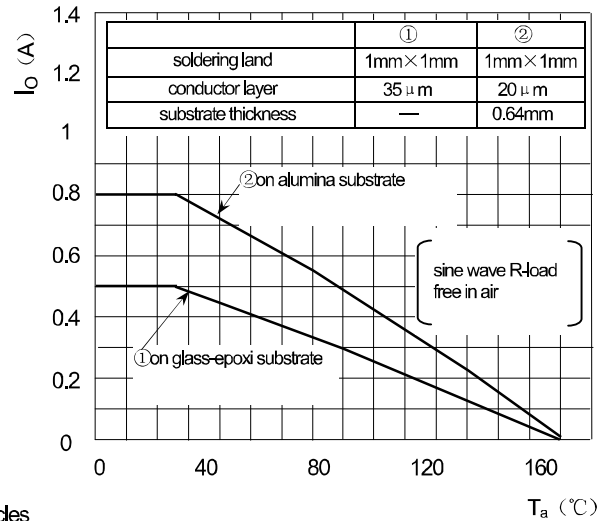
Forward Characteristics



P-I<sub>O</sub> Curve



Surge Forward Current Capability



I<sub>O</sub>-T<sub>a</sub> Curve